

NOV 27 2007

Patent

Customer No.: 31561  
Application No.: 10/709,179  
Docket No. 10544-US-PA

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicants : Chang et al.  
Application No. : 10/709,179  
Filed : April 19, 2004  
For : STACK-TYPE MULTI-CHIP PACKAGE AND METHOD  
OF FABRICATING BUMPS ON THE BACKSIDE OF A  
CHIP  
Art Unit : 2814  
Examiner : HA, NATHAN W.

**TRANSMITTAL LETTER**

+1-571-273-8300  
(Via fax: 1+2+ 8 pages)

ASSISTANT COMMISSIONER FOR PATENTS  
Alexandria, VA 22314

Dear Sir,

In response to the Advisory Action dated January 30, 2006, Appeal Brief filed April 12, 2006, and Reply Brief filed on September 8, 2006, please find the relevant papers in response thereof as follows:

- ☒ Request for Continued Examination in (2) pages;
- ☒ Preliminary Amendment in (8) pages.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date: Nov 27, 2007

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